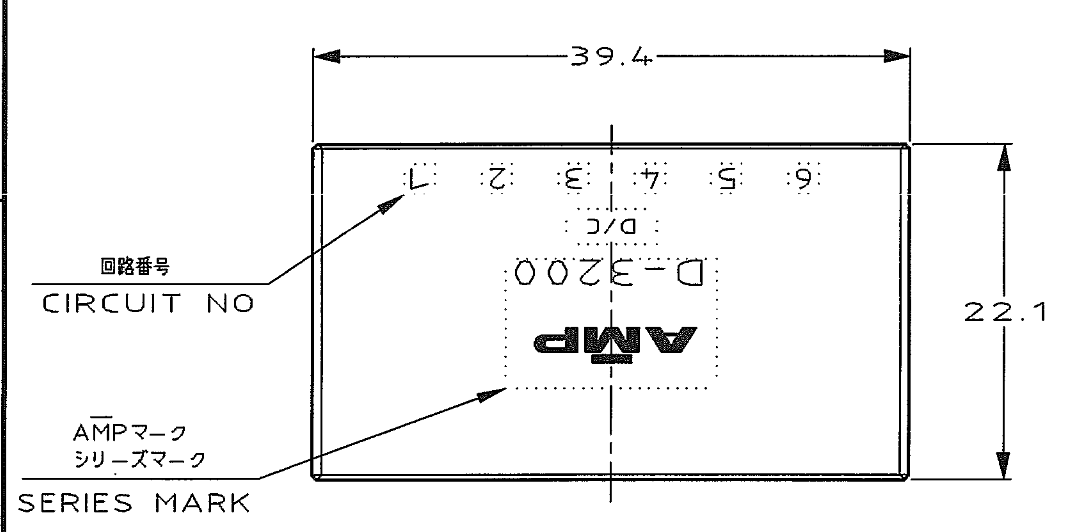
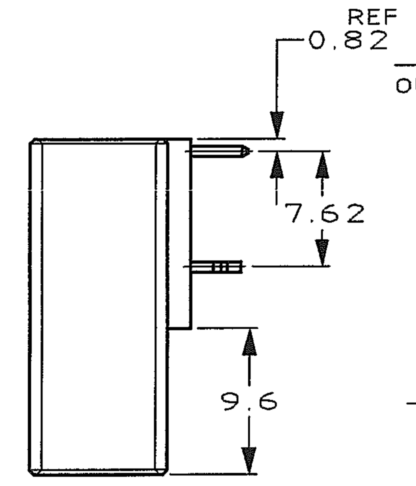
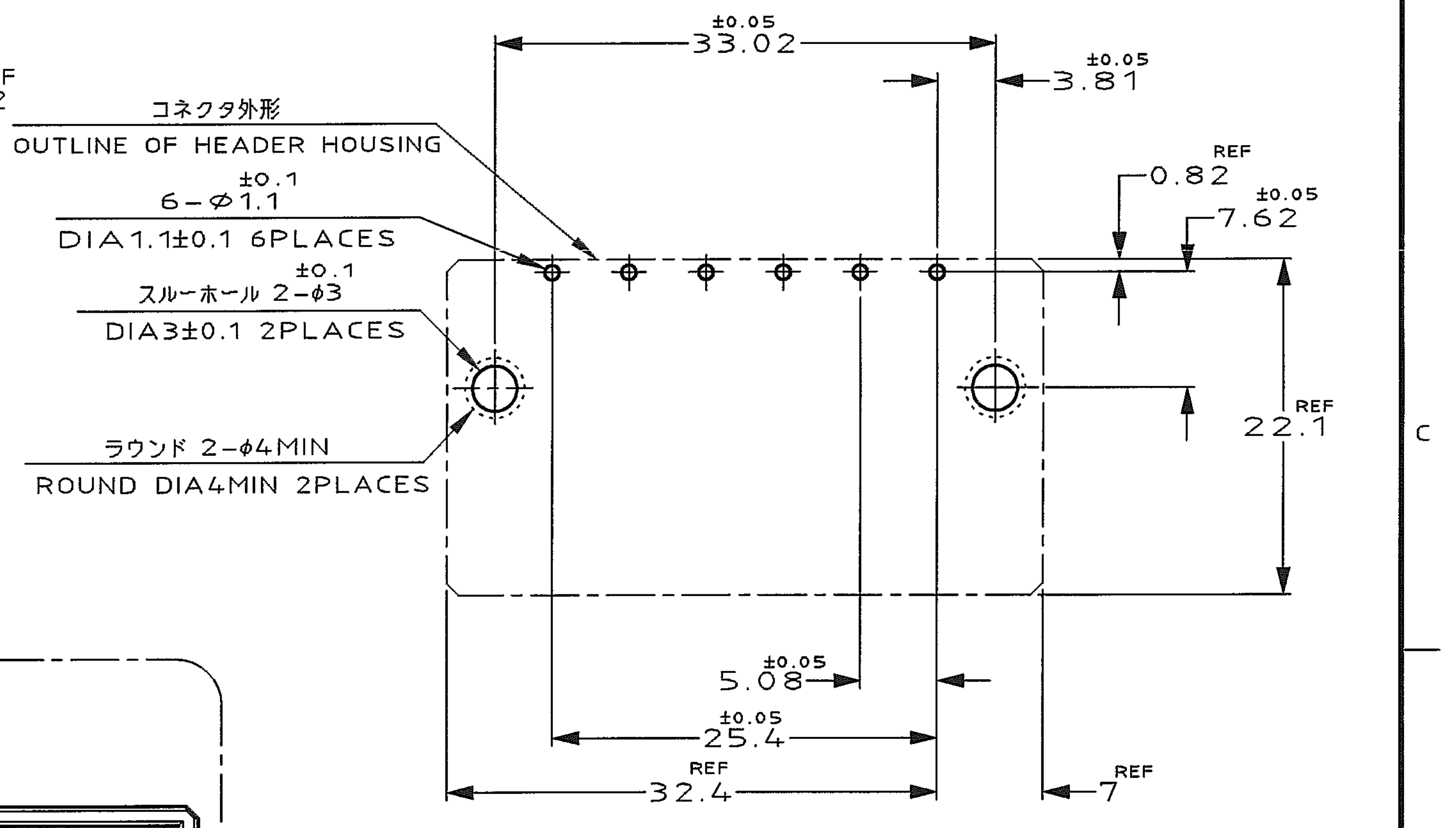
NUMBER 316131

3rd ANGLE PROJECTION

METRIC

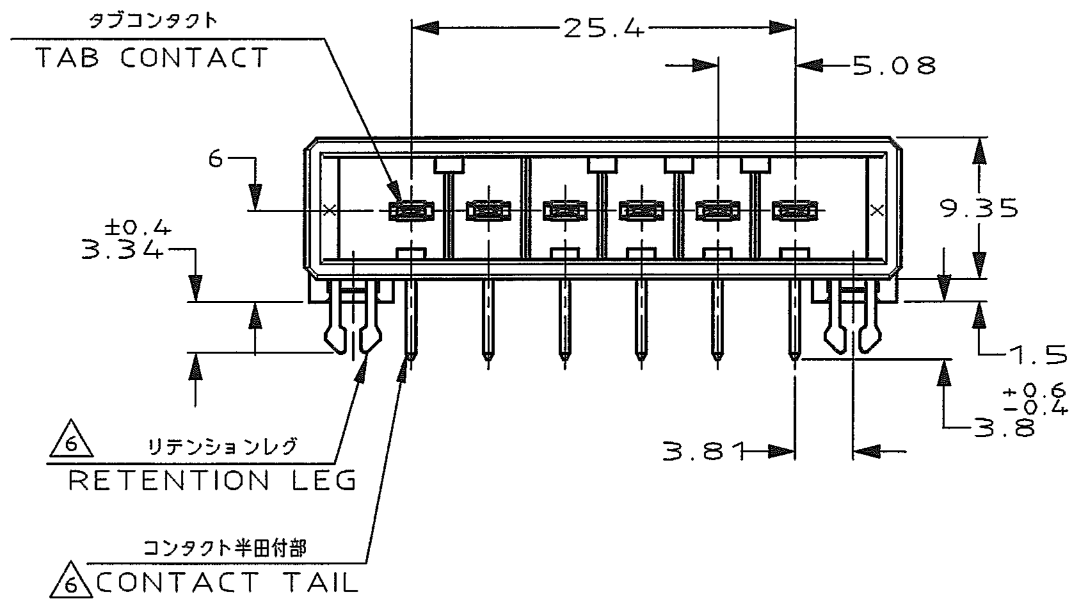


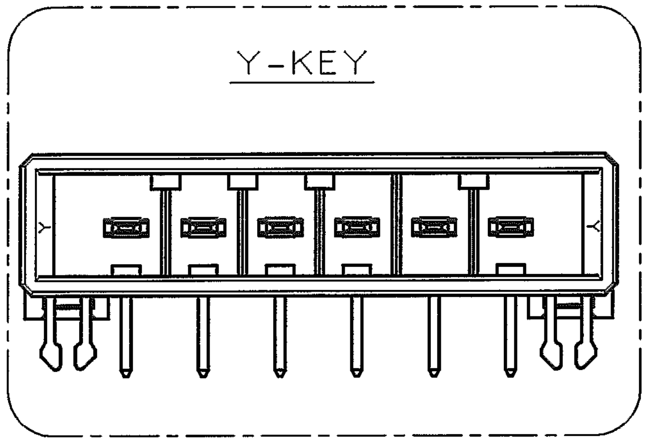




推奨基板取付け穴寸法
PC 基板厚：1.6±0.1
（非累積公差）
（コネクタ搭載面）

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)





NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY

2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING

3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING

4. FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL

~~5. FINISH(RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~

6. FINISH(RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注 記

1. 材料：ハウジング：ガラス入り熱可塑性ポリエステル樹脂
コンタクト：銅合金
リテンションレグ：銅合金

2. めっき：コンタクト：全面Ni下地
接触部：0.38μm MIN金めっき

3. めっき：コンタクト：全面Ni下地
接触部：0.76μm MIN金めっき

4. めっき：コンタクト：全面Ni下地
接触部：2.0 μm MINスズめっき

~~5. めっき：リテンションレグとコンタクト半田付部~~
~~：ニッケル下地の上に半田めっき~~

6. めっき：リテンションレグとコンタクト半田付部
：ニッケル下地の上にスズめっき

6	4	2-316131-5	Y
6	3	2-316131-3	Y
6	2	2-316131-2	Y
6	4	1-316131-5	X
6	3	1-316131-3	X
6	2	1-316131-2	X
(FINISH)		製品番号 (PART NO.)	KEY

LTR	REVISION RECORD	DR	CHK	DATE
B	REVISED(FJD0-0039-03)	TS	S.M	8/3 '03
A	REVISED(FJD0-0114-03)	TS	SM	25.APR '03
0	RELEASED (FJ00-2557-95)	KI	YI	31/JUL '95

tyco Electronics
Tyco Electoronics AMP K.K
Kawasaki,Japan

WIRE RANGE ~~mm²(AWG -)~~
INSULATION DIA ~~- mmφ~~
MATERIAL SEE NOTE 注記参照
FINISH SEE NOTE 注記参照
DR. K.IKEDA 26/JUL/'95
DE. K.IKEDA 26/JUL/'95
CHK. Y.ISHIKAWA 31/JUL/'95
APP. S.MANABE 31/JUL/'95

NAME
5 POS SINGLE ROW
HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200

一般公差
(GENERAL TOLERANCE)
10以下 : ±0.2
10を超え 30以下 : ±0.3
30を超え100以下 : ±0.4
角 度 : ±3'

SIZE A3
LOC J
NUMBER C-316131
SCALE 2-1
REV. B
SHEET 1 OF 1

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

AMP-J
REV.10/'83

(CUSTOMER DRAWING) 顧 客 用 図 面

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

TE Connectivity:

- 2-316131-2